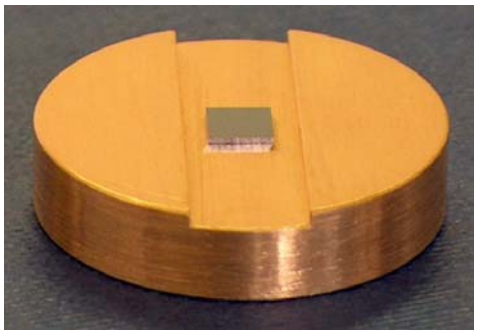
Mounted SAM data sheet SAM-λ-A-25.4g

GaAs chip area	standard:	4mm x 4mm
	optional:	other dimensions on request
Chip thickness	standard:	400 µm
	optional:	150 µm
Front side protection	the SAM is protected with a dielectric front layer.	

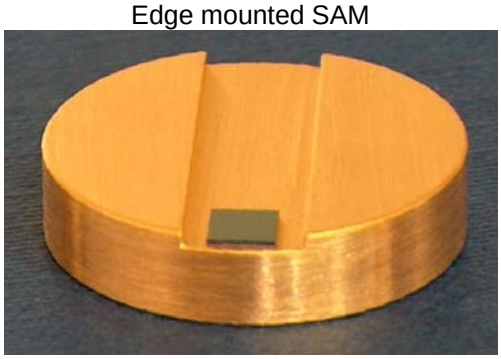
The SAM chip is glued on a gold plated Cu-cylinder with 25.4 mm Ø using a thermal conducting paste.

- The ***standard*** position of the SAM is at the center of the mount.
- ***Optional*** the SAM can be mounted at the edge of the mount without extra charges.

Center mounted SAM

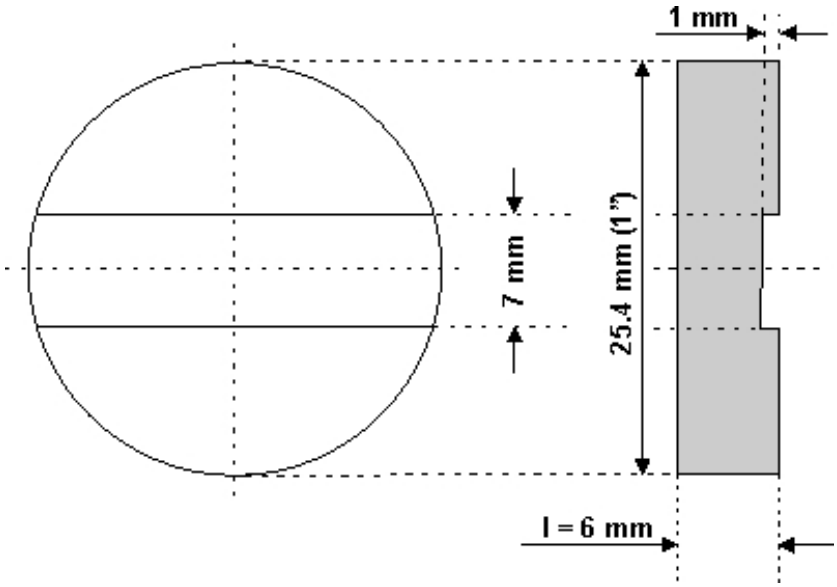


Edge mounted SAM



Mount

Cu-cylinder, ∅ = 25.4 mm
l = 6.0 mm



BATOP GmbH
Wildenbruchstraße 15
D-07745 Jena
Germany

Tel: +49 3641 634009 - 0
Fax: +49 3641 634009 - 20
E-mail: info@batop.de

Deutsche Bank Jena
Bank Code: 82070024
Account No: 3922655
IBAN: DE49 8207 0024 0392 2655 00

VAT Reg. No: DE 813698804
Tax Acc. No: 161/106/02514
Local Court Jena HRB 112769